Product Specification

Product:	**Silver-Palladium Paste/ Ag/Pd Paste**
Part Number:	**02H-1801**

Application Scope :

This product is suitable for use in thick-film circuits and chip resistors.

Usage Conditions :

Substrate	Alumina ceramics
Printing	200-300 mesh screen printing
Leveling	Let it level at room temperature for 5-15 minutes (adjust time based on actual leveling conditions).
Drying &Sintering	Sintering at 100-150°C for 10-15 minutes in a tunnel furnace with an air atmosphere, with a peak temperature of 850°C (recommended), for 10 minutes.
Thinner	ST-1000

Characteristics :

1. Paste Characteristics :

Characteristic		Standard	Test Method And Conditions
1	Fineness	≤5μm	FOG test
2	Viscosity	130-280Pa.s	Brookfield HBT (Boli Fei) viscometer, rotor model SC4-14/6R, operating at 10rpm and 25±1°C, with adjustable viscosity according to user requirements.

2. Characteristics After Curing :

Under the 1-sintering condition, the film thickness is 8-12 μm.
Check fired film produced under the conditions specified in 1）, (Film thickness is 8-12μm.)

Characteristics		Standard	Test Method And Conditions
3	Resistivity	≤6mΩ/☐	Test pattern 0.6mm×60mm
4	Adhesion Strength		Peel Test: 0.5mmφ Tin plated Cu wire soldered on 2mm×2mm Pad. Solder: 96.5Sn/0.5Cu Mildly activated flux used.
	Initial Adhesion	≥46.5N	

	Ageing Adhesion	≥26.3N	Aging conditions: 150°C, 24 hours

Save Conditions And Validity Period :

The product shall be stored in a sealed container at an ambient temperature of 5-25°C, with a shelf life of 1 year from the date of shipment.

Packaging Method :

Standard packaging, 1000g/can; samples are available in 200g small can packaging.